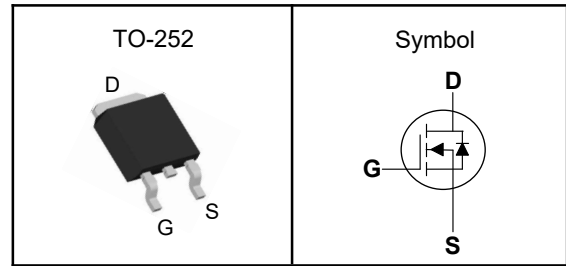


**650V Super Junction Power MOSFET**
**Features**

- Low drain-source on-resistance:  $R_{DS(ON)}=0.55\Omega(\text{typ})$
- Easy to control gate switching
- Enhancement mode:  $V_{th} = 2$  to  $4V$
- 100% avalanche tested
- RoHS compliant

**Applications**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger, Lighting

**Pin Description**


$V_{DSS}$	650	V
$R_{DS(ON)-Typ}$	550	m $\Omega$
$I_D$	8	A

**Absolute Maximum Ratings** ( $T_C=25^\circ\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
$V_{DSS}$	Drain-Source Voltage	650	V
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$T_J$	Maximum Junction Temperature	-55 to 150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	106	mJ
$I_{DM}^{①}$	300 $\mu\text{s}$ Pulse Drain Current Tested	31.2	A
$I_D$	Continuous Drain Current	8	A
$P_D$	Maximum Power Dissipation	80	W
$I_{AS}$	Avalanche Current	2.7	A
dv/dt	MOSFET dv/dt ruggedness, $V_{DS} = 0 \dots 400V$	50	V/ns
	Reverse diode dv/dt <sup>3</sup> $V_{DS}=0 \dots 400V, I_{SD} \leq I_D$	15	

**Thermal Characteristics**

Symbol	Parameter	Rating	Unit
$R_{\theta JA}^{③}$	Thermal Resistance Junction-Ambient <sup>1</sup>	62	$^\circ\text{C}/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	1.55	$^\circ\text{C}/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature  $150^\circ\text{C}$ .

Note ③ : Surface Mounted on  $1\text{in}^2$  FR-4 board with 1oz.



**650V Super Junction Power MOSFET**

**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)

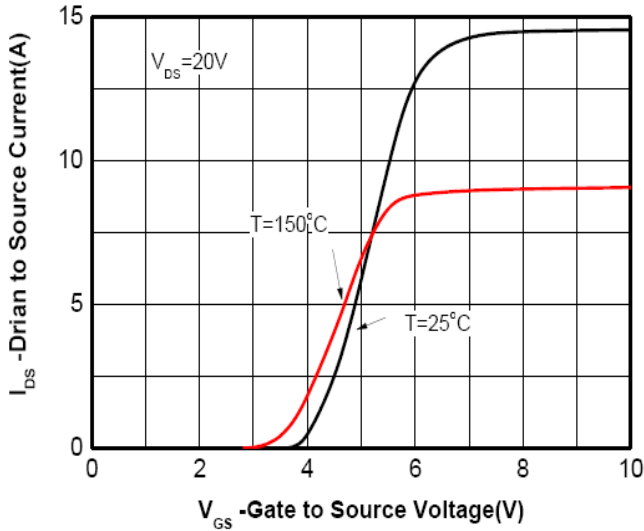
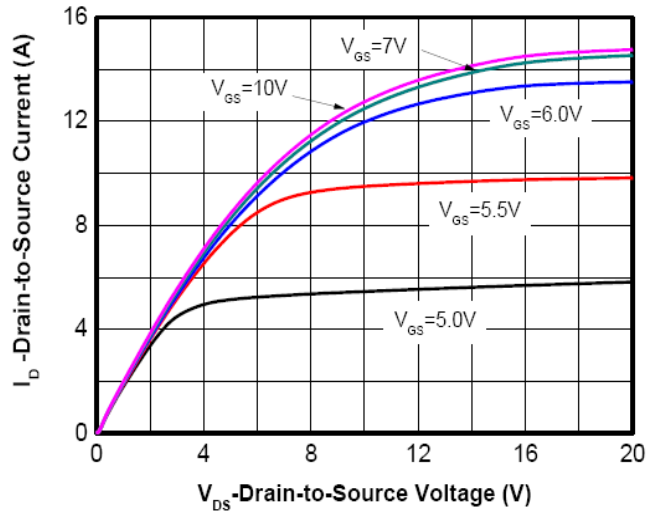
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
<b>Static Electrical Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	650	---	---	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=650V, V_{GS}=0V$	---	---	1	$\mu A$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0	---	4.0	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	$\pm 100$	nA
$R_{DS(on)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_D=3.5A$	---	550	650	m $\Omega$
<b>Dynamic Characteristics</b> <sup>⑤</sup>						
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=100V,$ Freq.=1.0MHz	---	480	---	pF
$C_{oss}$	Output Capacitance		---	22	---	
$C_{rss}$	Reverse Transfer Capacitance		---	1.1	---	
$T_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DD}=400V,$ $I_D=3.9A, R_G=10\Omega$	---	11	---	nS
$T_r$	Turn-on Rise Time		---	21	---	
$T_{d(off)}$	Turn-off Delay Time		---	40	---	
$T_f$	Turn-off Fall Time		---	31	---	
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DD}=400V, I_D=7.8A$	---	14	---	nC
$Q_{gs}$	Gate-Source Charge		---	3.2	---	
$Q_{gd}$	Gate-Drain Charge		---	5.6	---	
$R_g$	Gate resistance	f=1 MHz, open drain	---	9.6	---	$\Omega$
<b>Source-Drain Characteristics</b>						
$I_S$	Continuous Source Current		---	---	7.8	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current		---	---	31.2	A
$V_{SD}$	Diode Forward Voltage	$I_S=7.8A, V_{GS}=0V$	---	---	1.4	V
$t_{rr}$	Reverse recovery time	$I_S=3.9A, V_{GS}=0V$ $diF/dt=100A/\mu s$	---	205	---	ns
$Q_{rr}$	Reverse recovery charge		---	1.4	---	nC
$I_{rrm}$	Peak Reverse Recovery Current		---	12	---	A

Note ④: Pulse test (pulse width $\leq$ 300us, duty cycle $\leq$ 2%).

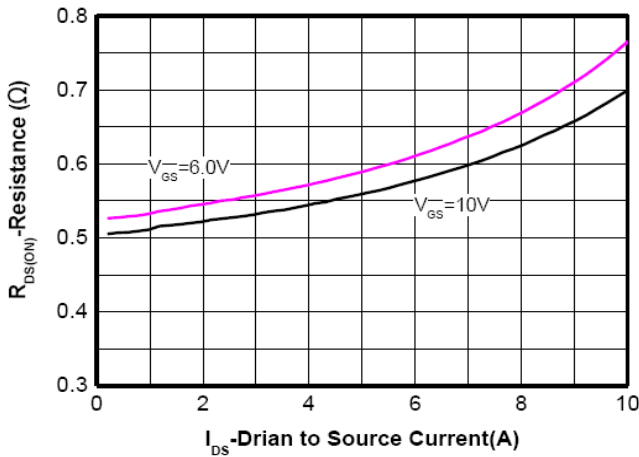
Note ⑤: Guaranteed by design, not subject to production testing.

**650V Super Junction Power MOSFET**
**Typical Characteristics**

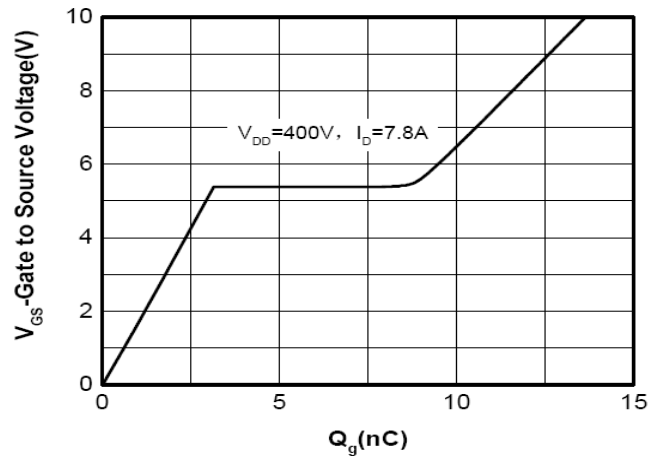
Typ. transfer characteristics


 Typ. output characteristics  $T_j = 25^\circ C$ 


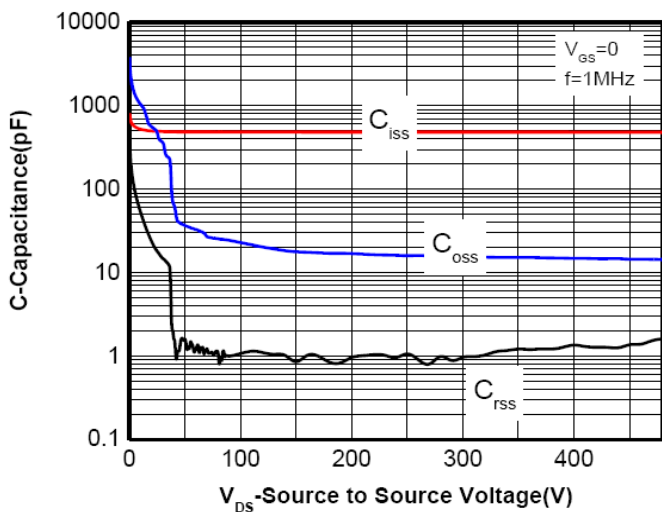
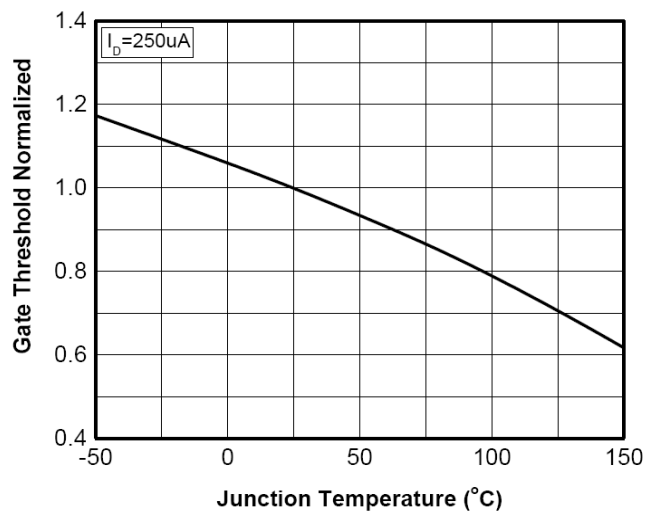
Typ. drain-source on-state resistance



Typ. gate charge characteristics

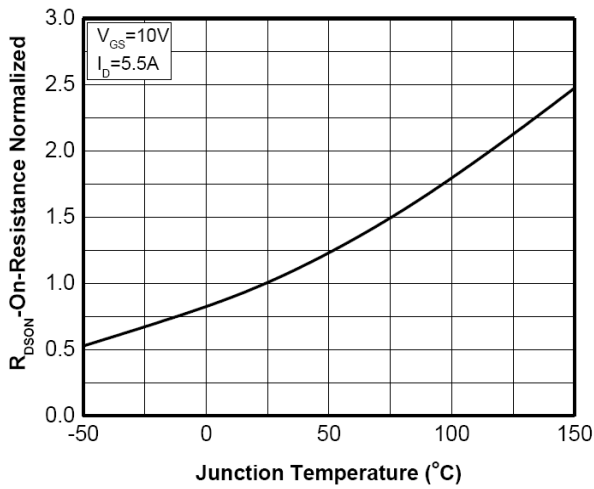


Typ. capacitances

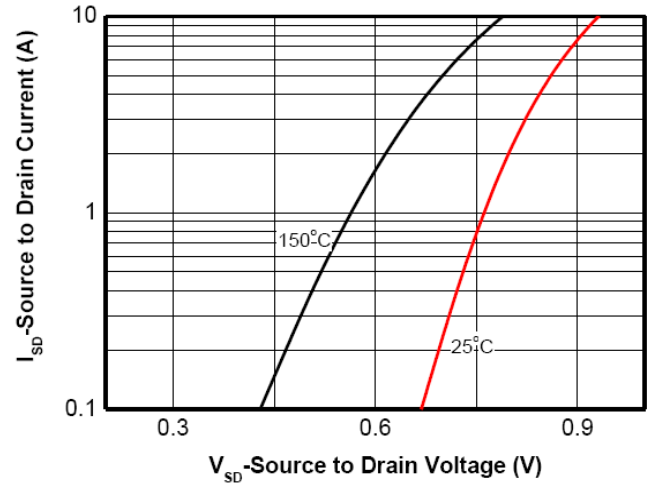

 Normalized  $V_{GS(th)}$  characteristics


**650V Super Junction Power MOSFET**

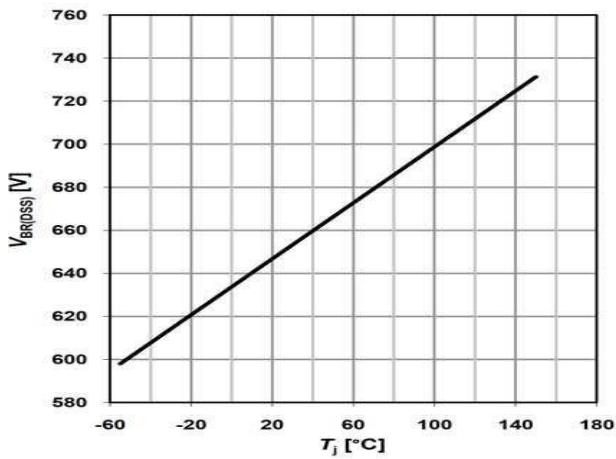
Normalized on-resistance vs temperature



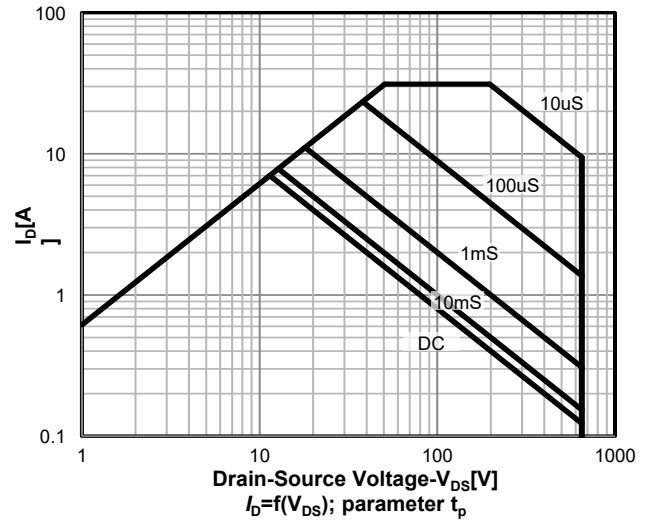
Forward characteristics of reverse diode



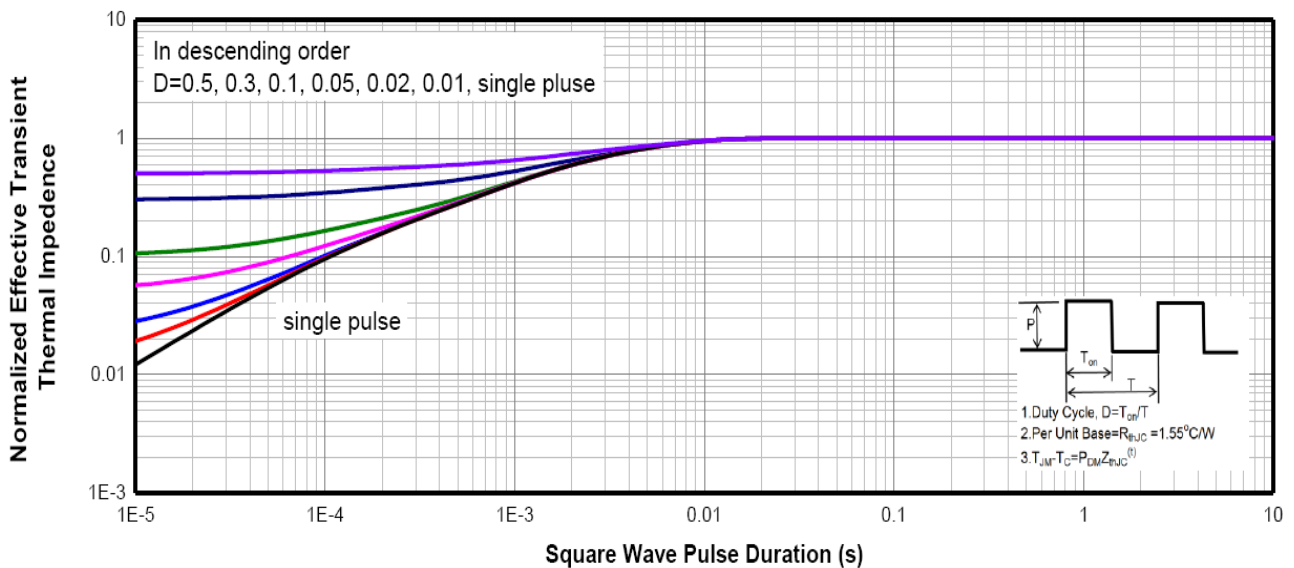
Drain-source breakdown voltage

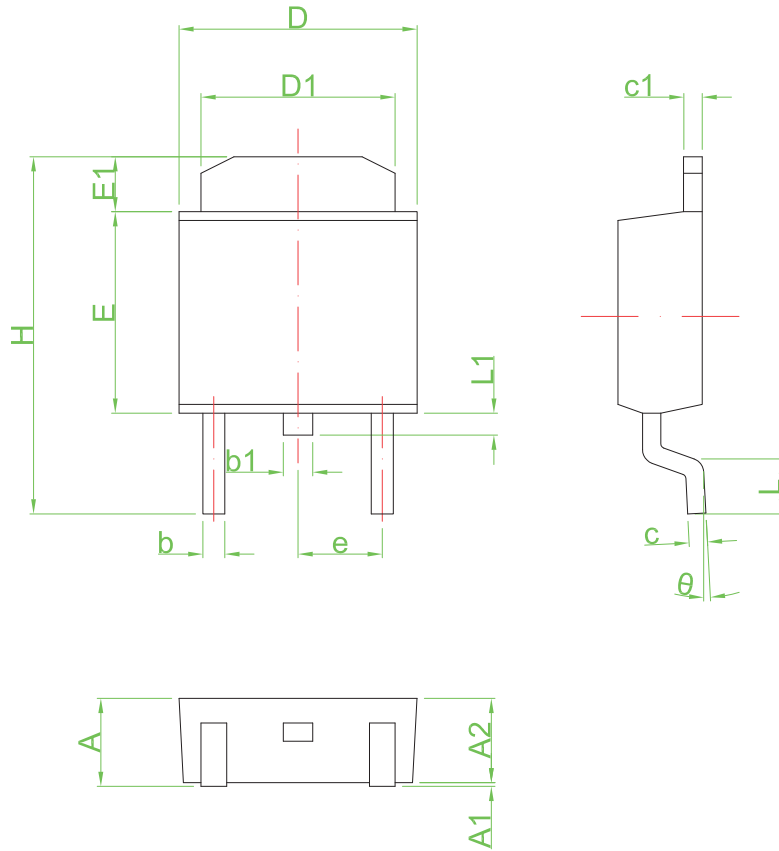


Safe operating area TC=25 °C



Max. transient thermal impedance



**650V Super Junction Power MOSFET**
**TO-252 Package Outline Dimensions**


Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Min	Max	Min	Max
A	2.25	2.65	0.089	0.104
A1	0.00	0.15	0.000	0.006
A2	2.20	2.40	0.087	0.094
b	0.50	0.70	0.020	0.028
b1	0.70	0.90	0.028	0.035
c	0.46	0.66	0.018	0.026
c1	0.46	0.66	0.018	0.026
D	6.30	6.70	0.248	0.264
D1	5.20	5.40	0.205	0.213
E	5.30	5.70	0.209	0.224
E1	1.40	1.60	0.055	0.063
H	9.40	9.90	0.370	0.390
e	2.30 TYP		0.09 TYP	
L	1.40	1.77	0.055	0.070
L1	0.50	0.70	0.020	0.028
θ	0°	8°	0°	8°